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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c56a-40-so

PIC16C5X

NOTES:

2.0 PIC16C5X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in this section. When placing orders, please use the PIC16C5X Product Identification System at the back of this data sheet to specify the correct part number.

For the PIC16C5X family of devices, there are four device types, as indicated in the device number:

- C, as in PIC16C54C. These devices have EPROM program memory and operate over the standard voltage range.
- LC, as in PIC16LC54A. These devices have EPROM program memory and operate over an extended voltage range.
- CR, as in PIC16CR54A. These devices have ROM program memory and operate over the standard voltage range.
- LCR, as in PIC16LCR54A. These devices have ROM program memory and operate over an extended voltage range.

2.1 UV Erasable Devices (EPROM)

The UV erasable versions offered in CERDIP packages, are optimal for prototype development and pilot programs.

UV erasable devices can be programmed for any of the four oscillator configurations. Microchip's PICSTART® Plus⁽¹⁾ and PRO MATE® programmers both support programming of the PIC16C5X. Third party programmers also are available. Refer to the

Third Party Guide (DS00104) for a list of sources.2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers expecting frequent code changes and updates, or small volume applications.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must be programmed.

Note 1: PIC16LC54C and PIC16C54A devices require OSC2 not to be connected while programming with PICSTART® Plus programmer.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration bit options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround-Production (SQTPSM) Devices

Microchip offers the unique programming service where a few user defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential. The devices are identical to the OTP devices but with all EPROM locations and configuration bit options already programmed by the factory.

Serial programming allows each device to have a unique number which can serve as an entry code, password or ID number.

2.5 Read Only Memory (ROM) Devices

Microchip offers masked ROM versions of several of the highest volume parts, giving the customer a low cost option for high volume, mature products.

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16C5X family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16C5X uses a Harvard architecture in which program and data are accessed on separate buses. This improves bandwidth over traditional von Neumann architecture where program and data are fetched on the same bus. Separating program and data memory further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 12 bits wide making it possible to have all single word instructions. A 12-bit wide program memory access bus fetches a 12-bit instruction in a single cycle. A twostage pipeline overlaps fetch and execution of instructions. Consequently, all instructions (33) execute in a single cycle except for program branches.

The PIC16C54/CR54 and PIC16C55 address 512 x 12 of program memory, the PIC16C56/CR56 address 1K x 12 of program memory, and the PIC16C57/CR57 and PIC16C58/CR58 address 2K x 12 of program memory. All program memory is internal.

The PIC16C5X can directly or indirectly address its register files and data memory. All special function registers including the program counter are mapped in the data memory. The PIC16C5X has a highly orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC16C5X simple yet efficient. In addition, the learning curve is reduced significantly.

The PIC16C5X device contains an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8 bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the W (working) register. The other operand is either a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a borrow and digit borrow out bit, respectively, in subtraction. See the SUBWF and ADDWF instructions for examples.

A simplified block diagram is shown in Figure 3-1, with the corresponding device pins described in Table 3-1 (for PIC16C54/56/58) and Table 3-2 (for PIC16C55/57).

7.0 I/O PORTS

As with any other register, the I/O Registers can be written and read under program control. However, read instructions (e.g., MOVF PORTB, W) always read the I/O pins independent of the pin's input/output modes. On RESET, all I/O ports are defined as input (inputs are at hi-impedance) since the I/O control registers (TRISA, TRISB, TRISC) are all set.

7.1 PORTA

PORTA is a 4-bit I/O Register. Only the low order 4 bits are used (RA<3:0>). Bits 7-4 are unimplemented and read as '0's.

7.2 PORTB

PORTB is an 8-bit I/O Register (PORTB<7:0>).

7.3 PORTC

PORTC is an 8-bit I/O Register for PIC16C55, PIC16C57 and PIC16CR57.

PORTC is a General Purpose Register for PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16C58 and PIC16CR58.

7.4 TRIS Registers

The Output Driver Control Registers are loaded with the contents of the W Register by executing the TRIS f instruction. A '1' from a TRIS Register bit puts the corresponding output driver in a hi-impedance (input) mode. A '0' puts the contents of the output data latch on the selected pins, enabling the output buffer.

Note: A read of the ports reads the pins, not the output data latches. That is, if an output driver on a pin is enabled and driven high, but the external system is holding it low, a read of the port will indicate that the pin is low.

The TRIS Registers are "write-only" and are set (output drivers disabled) upon RESET.

7.5 I/O Interfacing

The equivalent circuit for an I/O port pin is shown in Figure 7-1. All ports may be used for both input and output operation. For input operations these ports are non-latching. Any input must be present until read by an input instruction (e.g., MOVF PORTB, W). The outputs are latched and remain unchanged until the output latch is rewritten. To use a port pin as output, the corresponding direction control bit (in TRISA, TRISB, TRISC) must be cleared (= 0). For use as an input, the corresponding TRIS bit must be set. Any I/O pin can be programmed individually as input or output.

FIGURE 7-1: EQUIVALENT CIRCUIT FOR A SINGLE I/O PIN

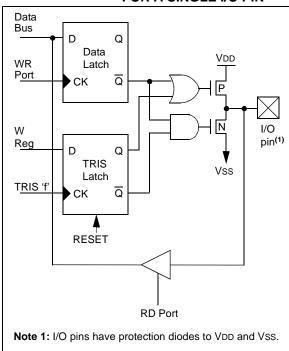


TABLE 7-1: SUMMARY OF PORT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on MCLR and WDT Reset
N/A	TRIS		I/O Control Registers (TRISA, TRISB, TRISC)							1111 1111	1111 1111
05h	PORTA	_	_						xxxx	uuuu	
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, — = unimplemented, read as '0', Shaded cells = unimplemented, read as '0'

10.0 INSTRUCTION SET SUMMARY

Each PIC16C5X instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C5X instruction set summary in Table 10-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers in that bank is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x1F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
х	Don't care location (= 0 or 1)
	The assembler will generate code with $x = 0$.
	It is the recommended form of use for com-
	patibility with all Microchip software tools.
d	Destination select;
	d = 0 (store result in W)
	d = 1 (store result in file register 'f')
	Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
WDT	Watchdog Timer Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination, either the W register or the
	specified register file location
[]	Options
()	Contents
\rightarrow	Assigned to
< >	Register bit field
€	In the set of
italics	User defined term (font is courier)

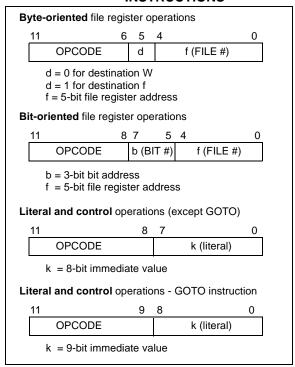
All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time would be 1 $\mu s.$ If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time would be 2 $\mu s.$

Figure 10-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS



ADDWF	Add	W	and f				
Syntax:	[lab	el]	ADDWF	f,d			
Operands:	$0 \le f \le 31$ $d \in [0,1]$						
Operation:	$(W) + (f) \rightarrow (dest)$						
Status Affected:	C, D)C, Z	<u> </u>				
Encoding:	00	01	11df	ff	ff		
Description:	Add the contents of the W register 'f'. If 'd' is 0 the resis stored in the W register. If 'd' '1' the result is stored back in register 'f'.						
Words:	1						
Cycles:	1						
Example:	ADD	WF	TEMP_RE	EG,	0		
Before Instr	uctio	n					
W		=	0x17				
TEMP_I		=	0xC2				
After Instruc	ction						
W		=	0xD9				
TEMP_I	REG	=	0xC2				

ANDWF	AND W with f					
Syntax:	[label] ANDWF f,d					
Operands:	$0 \le f \le 31$ $d \in [0,1]$					
Operation:	(W) .AND. (f) \rightarrow (dest)					
Status Affected:	Z					
Encoding:	0001 01df ffff					
Description:	The contents of the W register are AND'ed with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.					
Words:	1					
Cycles:	1					
Example:	ANDWF TEMP_REG, 1					
Before Instru W TEMP_I After Instruct W TEMP_I	= 0x17 $REG = 0xC2$ $tion$ $= 0x17$					

ANDLW	AND literal with W							
Syntax:	[label] ANDLW k							
Operands:	$0 \leq k \leq 255$							
Operation:	(W).AND. (k) \rightarrow (W)							
Status Affected:	Z							
Encoding:	1110 kkkk kkkk							
Description:	The contents of the W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.							
Words:	1							
Cycles:	1							
Example:	ANDLW H'5F'							
Before Instruction W = 0xA3 After Instruction W = 0x03								

BCF	Bit Clea	r f					
Syntax:	[label]	BCF f,t)				
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$						
Operation:	$0 \rightarrow (f < b >)$						
Status Affected:	None						
Encoding:	0100	bbbf	ffff				
Description:	Bit 'b' in	register 'f'	is cleared.				
Words:	1						
Cycles:	1						
Example:	BCF	FLAG_RE	EG, 7				
Before Instruction							
FLAG_REG = 0xC7 After Instruction							
FLAG_R		0x47					

11.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PIC MCUs and can be used to develop for this and other PIC microcontrollers. The MPLAB ICD utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial Programming™ protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

11.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in Stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable VDD and VPP supplies, which allow it to verify programmed memory at VDD min and VDD max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In Stand-alone mode, the PRO MATE II device programmer can read, verify, or program PIC devices. It can also set code protection in this mode.

11.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PIC devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

11.11 PICDEM 1 Low Cost PIC MCU Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A). PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE incircuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

11.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I²CTM bus and separate headers for connection to an LCD module and a keypad.

12.1 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial)

PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial)		Standard Operating Conditions (unless otherwise specifie Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial					
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions
D001	VDD	Supply Voltage PIC16C5X-RC PIC16C5X-XT PIC16C5X-10 PIC16C5X-HS PIC16C5X-LP	3.0 3.0 4.5 4.5 2.5		6.25 6.25 5.5 5.5 6.25	V V V	
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾		1.5*	_	V	Device in SLEEP Mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset		Vss	_	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	_	_	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current ⁽²⁾ PIC16C5X-RC ⁽³⁾ PIC16C5X-XT PIC16C5X-10 PIC16C5X-HS PIC16C5X-HS PIC16C5X-LP		1.8 1.8 4.8 4.8 9.0	3.3 3.3 10 10 20 32	mA mA mA mA mA	FOSC = 4 MHz, VDD = 5.5V FOSC = 4 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 20 MHz, VDD = 5.5V FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020	IPD	Power-down Current ⁽²⁾	_	4.0 0.6	12 9	μA μA	VDD = 3.0V, WDT enabled VDD = 3.0V, WDT disabled

^{*} These parameters are characterized but not tested.

- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, $\overline{MCLR} = VDD$; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in $k\Omega$.

[†] Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

12.5 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

DC CH	ARACTER	RISTICS	Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$ for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions	
D030	VIL	Input Low Voltage I/O ports MCLR (Schmitt Trigger) TOCKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1 (Schmitt Trigger)	Vss Vss Vss Vss Vss	11111	0.15 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.3 VDD	V V V V	Pin at hi-impedance PIC16C5X-RC only ⁽³⁾ PIC16C5X-XT, 10, HS, LP	
D040	VHYS	Input High Voltage I/O ports I/O ports I/O ports MCLR (Schmitt Trigger) TOCKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1 (Schmitt Trigger) Hysteresis of Schmitt	0.45 VDD 2.0 0.36 VDD 0.85 VDD 0.85 VDD 0.85 VDD 0.7 VDD		VDD VDD VDD VDD VDD VDD VDD VDD	V V V V V	For all $VDD^{(4)}$ $4.0V < VDD \le 5.5V^{(4)}$ VDD > 5.5 V PIC16C5X-RC only ⁽³⁾ PIC16C5X-XT, 10, HS, LP	
D060	lι∟	Trigger inputs Input Leakage Current (1,2) I/O ports MCLR MCLR TOCKI OSC1	-1 -5 -3 -3	0.5 0.5 0.5 0.5	+1 +5 +3 +3	μΑ μΑ μΑ μΑ μΑ	For VDD \leq 5.5 V: VSS \leq VPIN \leq VDD, pin at hi-impedance VPIN = VSS + 0.25V VPIN = VDD VSS \leq VPIN \leq VDD VSS \leq VPIN \leq VDD, PIC16C5X-XT, 10, HS, LP	
D080	Vol	Output Low Voltage I/O ports OSC2/CLKOUT		_	0.6 0.6	V V	IOL = 8.7 mA, VDD = 4.5V IOL = 1.6 mA, VDD = 4.5V, PIC16C5X-RC	
D090	Voн	Output High Voltage ⁽²⁾ I/O ports OSC2/CLKOUT	VDD - 0.7 VDD - 0.7	_		V V	IOH = -5.4 mA, VDD = 4.5V IOH = -1.0 mA, VDD = 4.5V, PIC16C5X-RC	

^{*} These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

^{2:} Negative current is defined as coming out of the pin.

^{3:} For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

^{4:} The user may use the better of the two specifications.

FIGURE 14-15: WDT TIMER TIME-OUT PERIOD vs. VDD⁽¹⁾

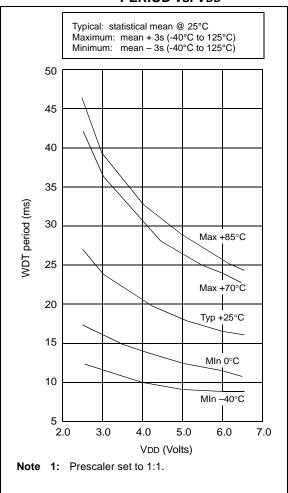


FIGURE 14-16: TRANSCONDUCTANCE (gm) OF HS OSCILLATOR vs. VDD

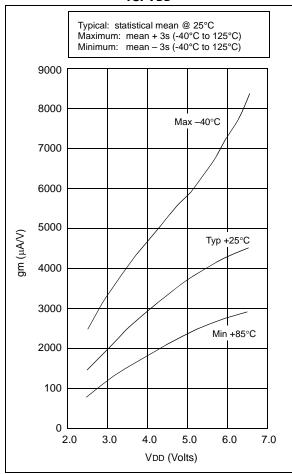


FIGURE 14-17: TRANSCONDUCTANCE (gm) OF LP OSCILLATOR vs. VDD

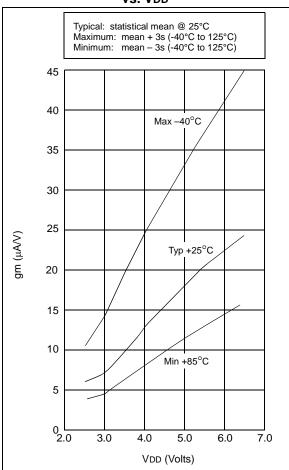


FIGURE 14-18: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD

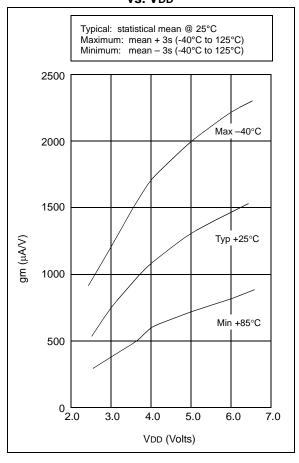


TABLE 14-2: INPUT CAPACITANCE FOR PIC16C54/56

Pin	Typical Capacitance (pF)				
Pin	18L PDIP	18L SOIC			
RA port	5.0	4.3			
RB port	5.0	4.3			
MCLR	17.0	17.0			
OSC1	4.0	3.5			
OSC2/CLKOUT	4.3	3.5			
T0CKI	3.2	2.8			

All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

TABLE 14-3: INPUT CAPACITANCE FOR PIC16C55/57

	Typical Capacitance (pF)				
Pin	28L PDIP (600 mil)	28L SOIC			
RA port	5.2	4.8			
RB port	5.6	4.7			
RC port	5.0	4.1			
MCLR	17.0	17.0			
OSC1	6.6	3.5			
OSC2/CLKOUT	4.6	3.5			
TOCKI	4.5	3.5			

All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

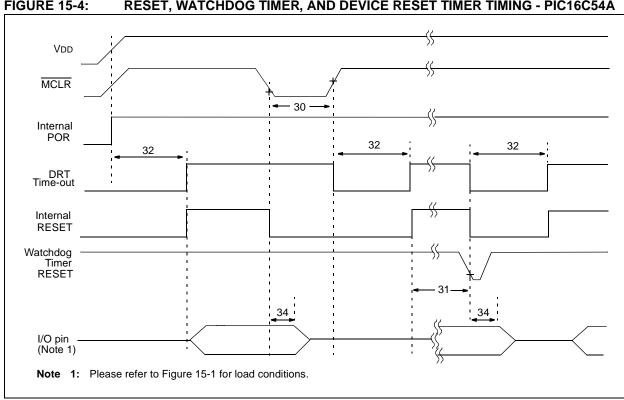


FIGURE 15-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C54A

TABLE 15-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C54A

./\BLL 10	THE TO C. RECEI, WITTERS TIMER, THE BETTER TELEFIT TIMER.							
Standard Operating Conditions (unless otherwise specified)								
Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}$							mmerci	al
AC Charac	cteristics	-40°C ≤ TA ≤ +85°C for industrial						
	-20° C \leq TA \leq +85 $^{\circ}$ C for industrial - PIC16LV54A-02I							- PIC16LV54A-02I
-40 °C \leq TA \leq +125°C for extended								
_								

Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	100* 1	_		ns μs	VDD = 5.0V VDD = 5.0V (PIC16LV54A only)
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
32	TDRT	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from MCLR Low	_	_	100* 1μs	ns —	(PIC16LV54A only)

These parameters are characterized but not tested.

Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-5: TIMER0 CLOCK TIMINGS - PIC16C54A

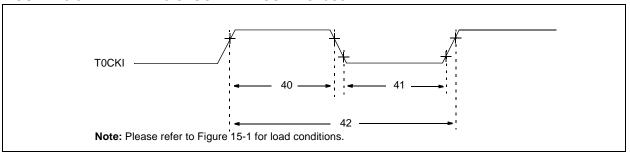


TABLE 15-4: TIMERO CLOCK REQUIREMENTS - PIC16C54A

TABLE 15-4:	HIMERO CLOC	K REQUIREMENTS	- PIC16C54A						
		Standard Operating Conditions (unless otherwise specified)							
		Operating Temperatu	ure 0°C ≤	T A ≤ + 7	70°C fo	or comn	nercial		
AC Cha	racteristics	-40°C ≤ TA ≤ +85°C for industrial							
			– 20°C ≤	T A ≤ + 8	35°C fo	or indus	trial - PIC16LV54A-02I		
			-40°C ≤	TA ≤ +1	25°C	for exte	nded		

Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width					
		- No Prescaler	0.5 Tcy + 20*	_	_	ns	
		- With Prescaler	10*	_	_	ns	
41	Tt0L	T0CKI Low Pulse Width					
		- No Prescaler	0.5 Tcy + 20*	_	_	ns	
		- With Prescaler	10*	_	_	ns	
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N	_	1		Whichever is greater. N = Prescale Value (1, 2, 4,, 256)

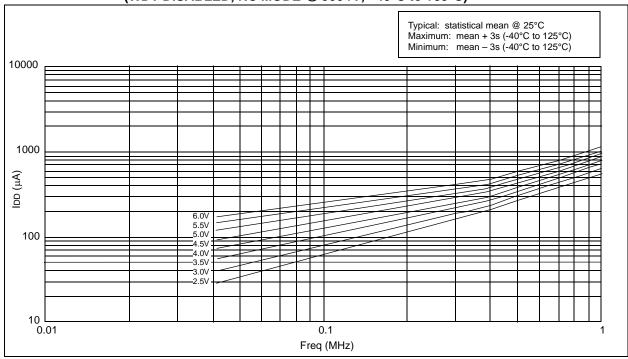
^{*} These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 PF, 25°C) Typical: statistical mean @ 25°C Maximum: mean + 3s (-40°C to 125°C) Minimum: mean - 3s (-40°C to 125°C) 10000 1000 IDD (μA) 100 5.5V 5.0V 4.5V 3.0V <u>—</u> 2.5V — 10 0.01 0.1 Freq (MHz)

FIGURE 16-14:

FIGURE 16-15: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 PF, -40°C to +85°C)



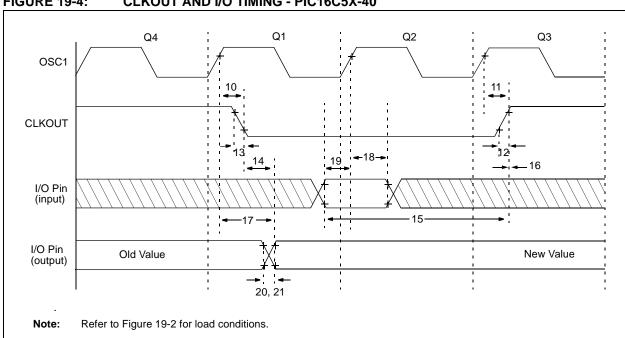


FIGURE 19-4: CLKOUT AND I/O TIMING - PIC16C5X-40

CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C5X-40 TABLE 19-2:

AC Characteristics		Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial								
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units				
10	TosH2ckL	OSC1↑ to CLKOUT↓ ^(1,2)	_	15	30**	ns				
11	TosH2ckH	OSC1↑ to CLKOUT↑ ^(1,2)	_	15	30**	ns				
12	TckR	CLKOUT rise time ^(1,2)	_	5.0	15**	ns				
13	TckF	CLKOUT fall time ^(1,2)	_	5.0	15**	ns				
14	TckL2ioV	CLKOUT↓ to Port out valid ^(1,2)	_	_	40**	ns				
15	TioV2ckH	Port in valid before CLKOUT ^(1,2)	0.25 TCY+30*	_	_	ns				
16	TckH2iol	Port in hold after CLKOUT ^(1,2)	0*	_	_	ns				
17	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out valid ⁽²⁾	_	_	100	ns				
18	TosH2iol	OSC1 [↑] (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	_	_	ns				
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	_	_	ns				
20	TioR	Port output rise time ⁽²⁾	_	10	25**	ns				
21	TioF	Port output fall time ⁽²⁾	_	10	25**	ns				

These parameters are characterized but not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Refer to Figure 19-2 for load conditions.

These parameters are design targets and are not tested. No characterization data available at this time.

Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 19-6: TIMERO CLOCK TIMINGS - PIC16C5X-40

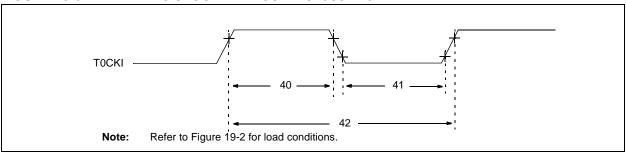


TABLE 19-4: TIMERO CLOCK REQUIREMENTS PIC16C5X-40

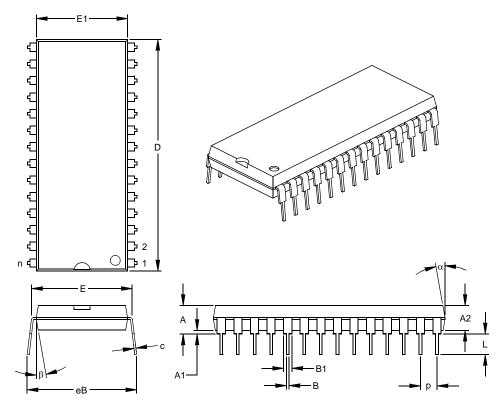
A	AC Charac	TERISTICS	Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial						
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions		
40	Tt0H	T0CKI High Pulse Width - No Prescaler	0.5 Tcy + 20*	_		ns			
		- With Prescaler	10*		—	ns			
41	TtOL	T0CKI Low Pulse Width - No Prescaler	0.5 Tcy + 20*	_	_	ns			
		- With Prescaler	10*		—	ns			
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N	_	_	ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)		

^{*} These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

28-Lead Plastic Dual In-line (P) - 600 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		INCHES*		N	IILLIMETERS	3	
Dimension	MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n		28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.160	.175	.190	4.06	4.45	4.83
Molded Package Thickness	A2	.140	.150	.160	3.56	3.81	4.06
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	Е	.595	.600	.625	15.11	15.24	15.88
Molded Package Width	E1	.505	.545	.560	12.83	13.84	14.22
Overall Length	D	1.395	1.430	1.465	35.43	36.32	37.21
Tip to Seating Plane	L	.120	.130	.135	3.05	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.030	.050	.070	0.76	1.27	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eВ	.620	.650	.680	15.75	16.51	17.27
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

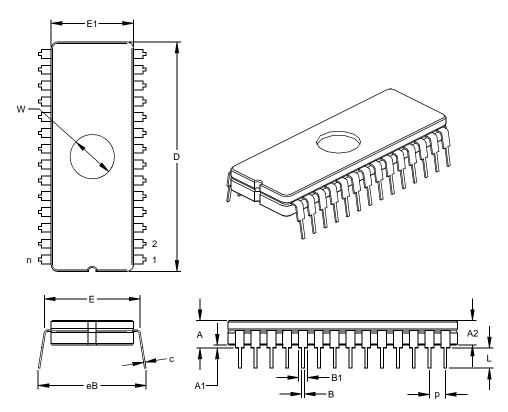
.010" (0.254mm) per side.

JEDEC Equivalent: MO-011 Drawing No. C04-079

^{*} Controlling Parameter § Significant Characteristic

28-Lead Ceramic Dual In-line with Window (JW) - 600 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		INCHES*		N	ILLIMETERS	3	
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.195	.210	.225	4.95	5.33	5.72
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.038	.060	0.38	0.95	1.52
Shoulder to Shoulder Width	Е	.595	.600	.625	15.11	15.24	15.88
Ceramic Pkg. Width	E1	.514	.520	.526	13.06	13.21	13.36
Overall Length	D	1.430	1.460	1.490	36.32	37.08	37.85
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	С	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.058	.065	1.27	1.46	1.65
Lower Lead Width	В	.016	.020	.023	0.41	0.51	0.58
Overall Row Spacing §	eВ	.610	.660	.710	15.49	16.76	18.03
Window Diameter	W	.270	.280	.290	6.86	7.11	7.37

^{*} Controlling Parameter § Significant Characteristic JEDEC Equivalent: MO-103 Drawing No. C04-013

PIC16C5X

NOTES: